

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajendra PENDSE

Application No.: 10/081,425

Filed: February 22, 2002

Title: **Apparatus and process for precise
encapsulation of flip chip interconnects**

Examiner: Scott B. GEYER

Group Art Unit: 2829

Date: January 9, 2003

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231 on January 9, 2003.

Signed

Linda Shaw

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

AMENDMENT

Dear Sir:

Responsive to the Office Action mailed August 9, 2002, kindly amend the application as follows.

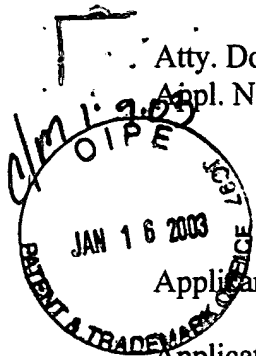
In the Specification

Please amend the specification, as shown on the attached "Attachment under Rule 1.121", as follows.

Replace the paragraph beginning at line 15 on page 3 (paragraph 0012) with the following rewritten paragraph.

-- In another general aspect the invention features apparatus for applying a precise volume of encapsulating resin to a chip, including a reservoir having a bottom, and means for dispensing a pool of encapsulating resin to a predetermined depth over the reservoir bottom. In some embodiments the reservoir is at least deep enough to accommodate a pool having a predetermined depth that approximates a bump standoff height on the chip. In some embodiments the means for dispensing the resin pool includes means for dispensing a measured volume of resin into the reservoir. In some embodiments the means for dispensing the resin pool includes means for

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